

Title of Change:	Update datasheet of EFC3J018NUZ, Changing from VGSS 10V to VGSS 12V		
Effective date:	28 March 2018		
Contact information:	Contact your local ON Semiconductor Sales Office or <Osamu Akaki@onsemi.com>		
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.		
Change category:	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other <u>Datasheet Update</u>		
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input checked="" type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____		
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: None	
Description and Purpose:			
This Product Bulletin updates the datasheet in order to change the characteristic of VGSS suitable for the customer's application use. Updating this datasheet does not change other characteristics of the current datasheet.			
<u>Old Datasheet</u>		<u>New Datasheet</u>	
SPECIFICATIONS		SPECIFICATIONS	
ABSOLUTE MAXIMUM RATINGS at Ta = 25°C (Note 1)		ABSOLUTE MAXIMUM RATINGS at Ta = 25°C (Note 1)	
Parameter	Symbol	Value	Unit
Source to Source Voltage	VSSS	20	V
Gate to Source Voltage	VGSS	±10	V
Maximum Operating Gate to Source Voltage (Note 2)	VGSS(OP)	±8	V
Source Current (DC)	IS	23	A
Source Current (Pulse) PW ≤ 100 μs, duty cycle ≤ 1%	ISP	100	A
Total Dissipation (Note 3)	PT	2.5	W
Junction Temperature	TJ	150	°C
Storage Temperature	Tstg	-55 to +150	°C
Note 1 : Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.			
Note 2 : Functional operation above the stresses listed in the recommended operating ranges is not implied. Extended exposure to stresses beyond the recommended operating ranges limits may affect device reliability			
<u>Old Datasheet</u>		<u>New Datasheet</u>	
SPECIFICATIONS		SPECIFICATIONS	
ABSOLUTE MAXIMUM RATINGS at Ta = 25°C (Note 1)		ABSOLUTE MAXIMUM RATINGS at Ta = 25°C (Note 1)	
Parameter	Symbol	Value	Unit
Source to Source Voltage	VSSS	20	V
Gate to Source Voltage	VGSS	±12	V
Maximum Operating Gate to Source Voltage (Note 2)	VGSS(OP)	±8	V
Source Current (DC)	IS	23	A
Source Current (Pulse) PW ≤ 100 μs, duty cycle ≤ 1%	ISP	100	A
Total Dissipation (Note 3)	PT	2.5	W
Junction Temperature	TJ	150	°C
Storage Temperature	Tstg	-55 to +150	°C
Note 1 : Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.			
Note 2 : Functional operation above the stresses listed in the recommended operating ranges is not implied. Extended exposure to stresses beyond the recommended operating ranges limits may affect device reliability			
List of Affected Standard Parts:			
EFC3J018NUZTDG			



Appendix A: Changed Products

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Product	Customer Part Number
EFC3J018NUZTDG	